SUNTEK
Advanced Materials

Room 1601,1608, Tower A, Zensun Int'l Plaza, Zhengzhou 450009, China
Tel: +86 371 65331060
sales@suntekmaterial.com
www.suntekmaterial.com

Grinding wheel for LED substrate

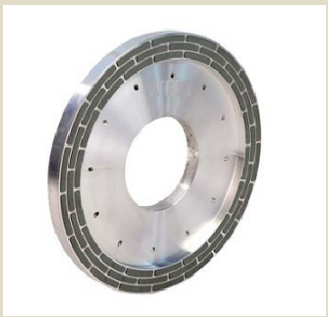
Workpiece:

Sapphire wafer, gallium arsenide and GaN wafer



Application:

Back thinning, suitable for NTS, Speedfam, WEC, Shuwa grinders and so on.

grinder	SHUWA	WEC	NTS
Back grinding wheel			
Type	Diameter: 175-350, Thickness: 22.5-47, Hole: 25-237		
Notes	SUNTEK provide resin bond, vitrified bond and compound bond back grinding wheel. Compound bond grinding wheel need not dressing any more, which can save much time and improve surface quality stability .		

The information contained in this product Information document is the sole property of Henan Suntek International Co., Ltd, (Suntek Material) and cannot be distributed outside Suntek Material or its Customers, entirely or by parts, without the prior consent of Suntek Material. The typical characteristics do not constitute a precise Customer Specifications, which has to be elaborated separately between the Customer and Suntek Material in the frame of a commercial offer. Only with this precise Customer Specification can Suntek Material be bound to any commitment or liability the quality of its products.